# LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司

# Winstar Display Co., LTD 華凌光電股份有限公司



WEB: <a href="https://www.winstar.com.tw">https://www.winstar.com.tw</a> E-mail: sales@winstar.com.tw

### **SPECIFICATION**

<b>CUSTOMER</b> :	~ ( )
MODULE NO.:	WO12864D3-TFH#

API	PRO	VED	BY:
$\mathbf{v}$		עשע	DI.

(FOR CUSTOMER USE ONLY)

**PCB VERSION:** 

DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
15			

VERSION	DATE	REVISED PAGE NO.		SUMMARY	
I	2019/12/17		_	Precautions CD Modules	in



MODLE NO:

華凌光電股份有限公司

### **RECORDS OF REVISION**

DOC. FIRST ISSUE

	T	T	
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/08/27		First issue
A	2012/11/14		Correct Electrical
			Characteristics
			Update Backlight
			Information
В	2013/05/15		Correct VDD
C	2013/10/31	40	Add Pull Tape
D	2015/03/12		Modify Contour
			Drawing(H=9.5mm) &
			Response Time
E	2016/01/27		Modify Precautions in use
	1 C >		of LCD Modules
			& Static electricity test
F	2016/03/10		Modify Length of FPC.
G	2016/11/21		Add FPC bending rule
Н	2019/08/27		Modify Material List of
			Components for RoHs
Ι	2019/12/17		Modify Precautions in use
			of LCD Modules

### **Contents**

- 1.Module Classification Information
- 2.Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13.Recommendable Storage

### 1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 128 \* 64 dot

Model serials no.

© Backlight Type: N $\rightarrow$ Without backlight T $\rightarrow$ LED, White L $\rightarrow$ LED, Full color

 $B\rightarrow EL$ , Blue green  $A\rightarrow LED$ , Amber  $J\rightarrow DIP$  LED, Blue  $D\rightarrow EL$ , Green  $R\rightarrow LED$ , Red  $K\rightarrow DIP$  LED, White

W→EL, White O→LED, Orange E→DIP LED, Yellow Green

 $M\rightarrow EL$ , Yellow Green  $G\rightarrow LED$ , Green  $H\rightarrow DIP$  LED, Amber  $F\rightarrow CCFL$ , White  $P\rightarrow LED$ , Blue  $I\rightarrow DIP$  LED, Red

 $Y\rightarrow$ LED, Yellow Green  $X\rightarrow$ LED, Dual color  $G\rightarrow$ LED, Green  $C\rightarrow$ LED, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$  Positive, Gray  $F \rightarrow FSTN$  Positive  $I \rightarrow HTN$  Negative, Black  $K \rightarrow FSC$  Negative  $U \rightarrow HTN$  Negative, Blue  $S \rightarrow FSC$  Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

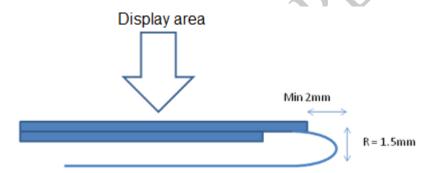
Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

### 2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending



(12)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

## **3.General Specification**

Item	Dimension	Unit
Number of Characters	128 x 64 dots	_
Module dimension	80.0x 54.0 x 9.5	mm
View area	70.7 x 38.8	mm
Active area	66.52 x 33.24	mm
Dot size	0.48 x0.48	mm
Dot pitch	0.52 x 0.52	mm
LCD type	FSTN Positive, Transflective (In LCD production, It will occur slightly color of can only guarantee the same color in the same based on the same based of the same based on th	
Duty	1/64 , 1/9 Bias	
View direction	6 o'clock	
Backlight Type	LED White	
IC	ST7565P	

# **4.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Power Supply Voltage	VDD	-0.3	_	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	_	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3	<u> </u>	V0+0.3	V

## **5.Electrical Characteristics**

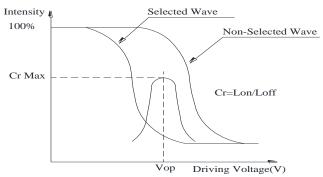
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	2.7		3.3	V
		Ta=-20°C	10.0	10.2	10.4	V
Supply Voltage For LCM	$V_0$ - $V_{SS}$	Ta=25°C	9.8	10.0	10.2	v
*NOTE		Ta=70°C	9.6	9.8	10.0	y
Input High Volt.	$V_{ m IH}$	_	$0.8~\mathrm{V_{DD}}$	_	$V_{DD}$	V
Input Low Volt.	$V_{IL}$	_	Vss	<b>├</b> (	$0.2~\mathrm{V_{DD}}$	V
Output High Volt.	$V_{\mathrm{OH}}$	_	$0.8\mathrm{V}_\mathrm{DD}$		$V_{ m DD}$	V
Output Low Volt.	$V_{\mathrm{OL}}$	-	Vss	_	$0.2V_{DD}$	V
Supply Current(No include  LED Backlight)	$I_{\mathrm{DD}}$	\Q\ \\		0.6	1	mA

NOTE: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

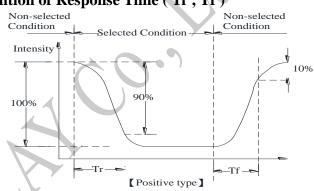
### **6.Optical Characteristics**

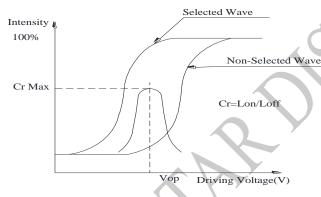
Item	Symbol	Condition	Min	Тур	Max	Unit
	$\theta$	CR≧2	0	_	30	$\phi = 180^{\circ}$
View Angle	θ	CR≧2	0	_	60	$\phi = 0^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	5	_	_
Dagaga Tima	T rise	_	_	200	300	ms
Response Time	T fall	_	_	250	350	ms

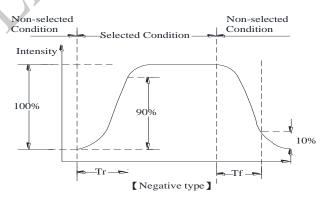
### **Definition of Operation Voltage (Vop)**



### **Definition of Response Time (Tr, Tf)**







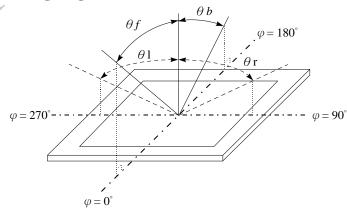
#### **Conditions:**

Operating Voltage : Vop Frame Frequency : 64 HZ

Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Driving Waveform : 1/N duty , 1/a bias

### Definition of viewing angle( $CR \ge 2$ )



## **7.Interface Pin Function**

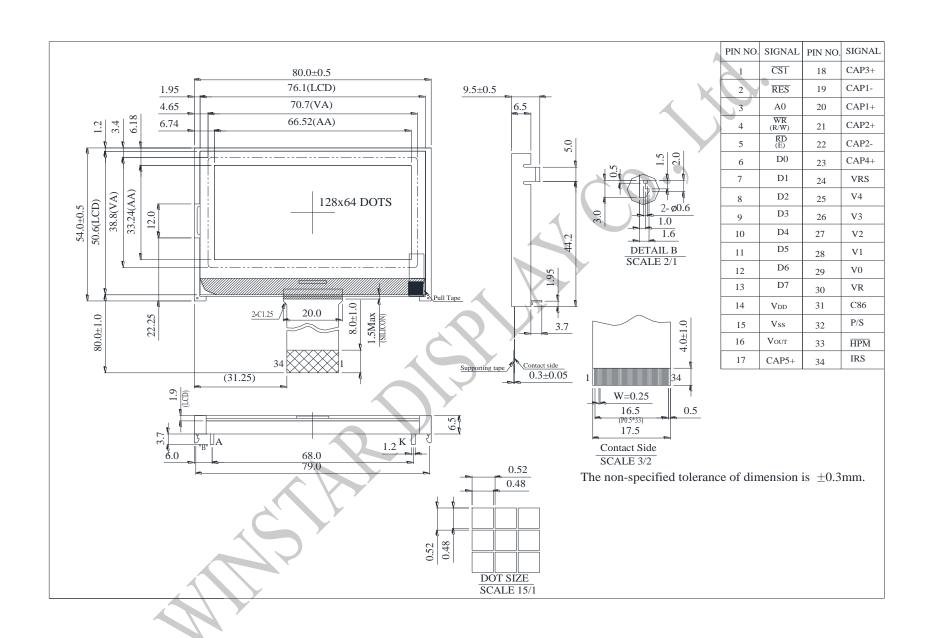
Pin No.	Symbol	Level	Description
1	/CS1	I	The chip select signal
2	/RES	I	When RES is set to "L", the setting are initialized.
3	A0	I	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command.  A0 = "H": Indicates that D0 to D7 are display data.  A0 = "L": Indicates that D0 to D7 are control data.
4	/WR(R/W)	I	<ul> <li>When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the 8080 MPU and is LOW-active. The signals on the data bus are latched at the rising edge of the /WR signal.</li> <li>When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the 6800 MPU and decides the access type: When R/W = "H": Read.</li> <li>When R/W = "L": Write.</li> </ul>
5	/RD(E)	I	<ul> <li>When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the 8080 MPU and is LOW-active.</li> <li>The data bus is in an output status when this signal is "L".</li> <li>When connected to 6800 series MPU, this pin is treated as the "E" signal of the 6800 MPU and is HIGH-active.</li> <li>This is the enable clock input terminal of the 6800 Series MPU.</li> </ul>
6~13	D0~D7	I/O	Data bus line
14	VDD	Power Supply	Power supply
15	VSS	Power Supply	Ground
16	VOUT	О	DC/DC voltage converter. Connect a capacitor between this terminal and vss or VDD
17	CAP5+		
18	CAP3+		
19	CAP1-		DC/DC voltage convented
20	CAP1+	О	DC/DC voltage converter
21	CAP2+		
22	CAP2-		

23	CAP4+							
24	VRS	Power Supply		he internal-outp pply voltage	out VREG	power supp	oly for the	LCD
25	V4							
26	V3							
27	V2	Power	This is a	multi-level pov	ver supply t	for the liqui	d crystal dri	ve.
28	V1	Supply		•	11 7			
29	V0						<b>Y</b>	
30	VR	I	VSS and IRS = "L used.	oltage regulator V0 through a r ": the V0 volt ": the V0 volta	esistive vol age regula	tage dividentor internal	r. resistors are	e not
31	C86	Ι	IRS = "H": the V0 voltage regulator internal resistors are used.  This is the MPU interface selection pin.  I C86 = "H": 6800 Series MPU interface.  C86 = "L": 8080 Series MPU interface					
		R	This is the parallel data input/serial data input switch terminal.  P/S = "H": Parallel data input.  P/S = "L": Serial data input.  The following applies depending on the P/S status					
			P/S	Data/Command	Data	Read/Write	Serial Clock	
32	P/S	I	"H"	A0	D0 to D7	/RD, /WR	Х	
	AP AP		"L"	A0	SI (D7)	Write only	SCL (D6)	
			When P/S = "L", D0 to D5 fixed "H".  /RD (E) and /WR (R/W) are fixed to either "H" or "L".  With serial data input, It is impossible read data from RAM					
33	/HPM	I	This is the power control terminal for the power supply circuit for liquid crystal drive.					

34	IRS	I	This terminal selects the resistors for the V0 voltage level adjustment.  IRS = "H": Use the internal resistors  IRS = "L": Do not use the internal resistors. The V0 voltage level is regulated by an external resistive voltage divider attached to the VR terminal
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# **8.Contour Drawing**





## 9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Not e
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs ▲	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90% RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= $\pm 600$ V(contact), $\pm 800$ v(air), RS= $330\Omega$ CS= $150$ pF 10 times	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

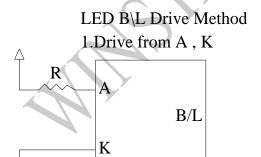
## **10.Backlight Information**

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	96	120	mA	V=3.5V
Supply Voltage	v	3.4	3.5	3.6	V	- ×0
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	840	1050	_	CD/M <sup>2</sup>	ILED=96mA
LED Life Time					1	ILED=96mA
(For Reference	_	_	50K	-	Hr.	25°C,50-60%RH,
only)						(Note 1)
Color	White			YY		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



# 11.Inspection specification

NO	Item	Criterion				AQL
		Missing vertical	, horizonta	al segment, segmen	nt contrast defect.	
		Missing characte	er, dot or	icon.		
		Display malfund	ction.			
01	Electrical	No function or r	o display.			0.65
01	Testing	Current consum	ption exce	eds product specif	ïcations.	0.65
		LCD viewing ar	ngle defect	•	~ (	
		Mixed product t	ypes.			
		Contrast defect.				
	Black or	2.1 White and h	lack snots	on display $\leq 0.25$	mm, no more than	
02	white spots on	three white or bl	_		min, no more than	2.5
02	LCD (display		-	-	or lines within 3mm	2.3
	only)	2.2 Densery space		ore than two spots	of times within 5imin	
		3.1 Round type	: As follow	ving drawing		
		$\Phi = (x + y) / 2$		SIZE	Acceptable Q TY	
				Φ≦0.10	Accept no dense	
				$0.10 < \Phi \le 0.20$	2	
				$0.20 < \Phi \leq 0.25$	1	2.5
				0.25 < Ф	0	2.3
	LCD black	X				
	spots, white	→ _ ←	<u> </u>			
03	spots, white	• .	<b>x</b> Y			
	contamination		T			
	(non-display)	3.2 Line type : (	As follow	ing drawing)		
	4		Length	Width	Acceptable Q TY	
		~ /¥ w		W≦0.02	Accept no dense	
<		→ i i i←	L≦3.0	$0.02 < W \le 0.03$	2	2.5
		, <b>a.</b>	L≦2.5	$0.03 < W \le 0.05$		
1				0.05 < W	As round type	

04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5
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NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD blac	ck spots, white spots, co	ntamination	
		Symbols Define:			
		x: Chip length y	: Chip width z: Ch	ip thickness	
		k: Seal width t:	Glass thickness a: LC	CD side length	
		L: Electrode pad length	ı:		
		6.1 General glass chip:			
		6.1.1 Chip on panel sur	face and crack between	panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x ≤ 1/8a	2.5
	glass	$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a	2.5
		⊙ If there are 2 or more 6.1.2 Corner crack:	e chips, x is total length	of each chip.	
			Cli i li		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	$x \le 1/8a$	
		$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a	
		⊙ If there are 2 or more	e chips, x is the total len	gth of each chip.	

NO	Item	Criterion			AQL
		Symbols:			
		•	ip width z: Chip	thickness	
			-	side length	
		L: Electrode pad length		•	
		6.2 Protrusion over termina	1:		
		6.2.1 Chip on electrode pad	:		
06	Glass		≦ 1/8a	$\frac{z}{z} \stackrel{\text{Chip thickness}}{\text{Chip thickness}}$	2.5
		y: Chip width	x: Chip length	z: Chip thickness	
		y≦ L	x ≤ 1/8a	$0 < z \le t$	
		⊙ If the chipped area touch			
		remain and be inspected acc			
	~	⊙ If the product will be hear	=	=	
		be damaged.	•		
, 4		6.2.3 Substrate protuberanc	e and internal crack.		
		X	y: width	x: length	
			$y \le 1/3L$	$x \leq a$	
		y	•		
		389			

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
00	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5
08	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the	2.5
		seal area on the PCB. And there should be no more than three	
		places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB、COB	10.6 Parts on PCB must be the same as on the production	0.65
10	TCD COD	characteristic chart. There should be no wrong parts, missing	
		parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5
		screw hold pad, make sure it is smoothed down.	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
	16	X	
		$X * Y \le 2mm^2$	2.7
, <		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	2.5
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to sever.	
	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

### **12.Material List of Components for**

### RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limi	Above limited value is set up according to RoHS.									

- 2.Process for RoHS requirement : (only for RoHS inspection)
  - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.  $: 235\pm5^{\circ}C$ ;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

### 13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



•		Feedback Sheet
lodule Number:		Page: 1
1 · Panel Specification :	_ n	
1. Panel Type:	Pass	□ NG ,
2. View Direction:	Pass	□ NG ,
3. Numbers of Dots:	Pass	□ NG ,
4. View Area:	Pass	□ NG ,
5. Active Area:	Pass	□ NG ,
6. Operating Temperature:	Pass	□ NG ,
7. Storage Temperature:	Pass	□ NG ,
8. Others:		
2 · <u>Mechanical Specification</u> :		,
1. PCB Size:	Pass	□ NG,
2. Frame Size:	Pass	□ NG ,
3. Materal of Frame:	Pass	□ NG ,
4. Connector Position:	☐ Pass	□ NG,
5. Fix Hole Position:	Pass	□ NG ,
6. Backlight Position:	☐ Pass	□ NG ,
7. Thickness of PCB:	☐ Pass	□ NG ,
8. Height of Frame to PCB:	☐ Pass	□ NG ,
9. Height of Module:	Pass	□ NG ,
10. Others:	☐ Pass	□ NG ,
3 · Relative Hole Size :		
1. Pitch of Connector:	☐ Pass	□ NG ,
2. Hole size of Connector:	Pass	□ NG ,
3. Mounting Hole size:	Pass	□ NG ,
4. Mounting Hole Type:	Pass	□ NG ,
5. Others:	Pass	□ NG ,
4 · Backlight Specification :		
1. B/L Type:	Pass	□ NG ,
2. B/L Color:	Pass	□ NG ,
3. B/L Driving Voltage (Refere	ence for LED T	
4. B/L Driving Current:	☐ Pass	□ NG,
5. Brightness of B/L:	☐ Pass	□ NG,
6. B/L Solder Method:	☐ Pass	□ NG,
7. Others:	Pass	□ NG,
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5 · Electronic Characteristics o	f Module:	
1. Input Voltage:	☐ Pass	□ NG ,
2. Supply Current:	Pass	□ NG ,
3. Driving Voltage for LCD:	Pass	□ NG ,
4. Contrast for LCD:	Pass	□ NG ,
5. B/L Driving Method:	☐ Pass	□ NG ,
6. Negative Voltage Output:	Pass	□ NG ,
7. Interface Function:	Pass	□ NG ,
8. LCD Uniformity:	Pass	□ NG ,
9. ESD test:	Pass	□ NG,
10. Others:	Pass	□ NG,